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(54) Title: HEAT-CURABLE RESIN COMPOSITION

(57) Abstract: The present invention relates to a resin composition comprising an at least bifunctional prepolymer (A) curable under the action of heat, a telechelic elastomer and a particulate material having an elastomeric core and a thermoplastic shell. Layers and patterns which are produced using the formulation according to the invention have excellent adhesion properties, chemical stability, good electrical properties and high resistance to rapid temperature ranges. The compositions are suitable in particular as solder resists in the production of circuit boards.



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